

S'attaquer aux problématiques de test et de fiabilité des accélérateurs IA analogiques et mixtes

Martin Andraud

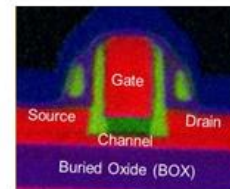
FETCH'26

The FAMES pilot line

- FAMES is an EU pilot line, promoting semiconductor technologies in Europe
- Driven by CEA-Leti
- **The role of my group:** demonstrating AI acceleration systems based on eNVMs

FD-SOI

10nm and 7nm



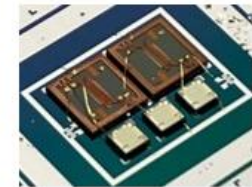
Radiofrequency components

switches, filters, and capacitors



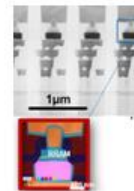
Small inductors for DC-DC converters

Power Management Integrated Circuits (PMIC)



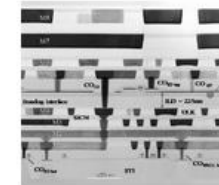
Several types of embedded non-volatile memories

OxRAM, FeRAM, MRAM and FeFETs



3D integration

heterogeneous and sequential



Sustainability and eco-design

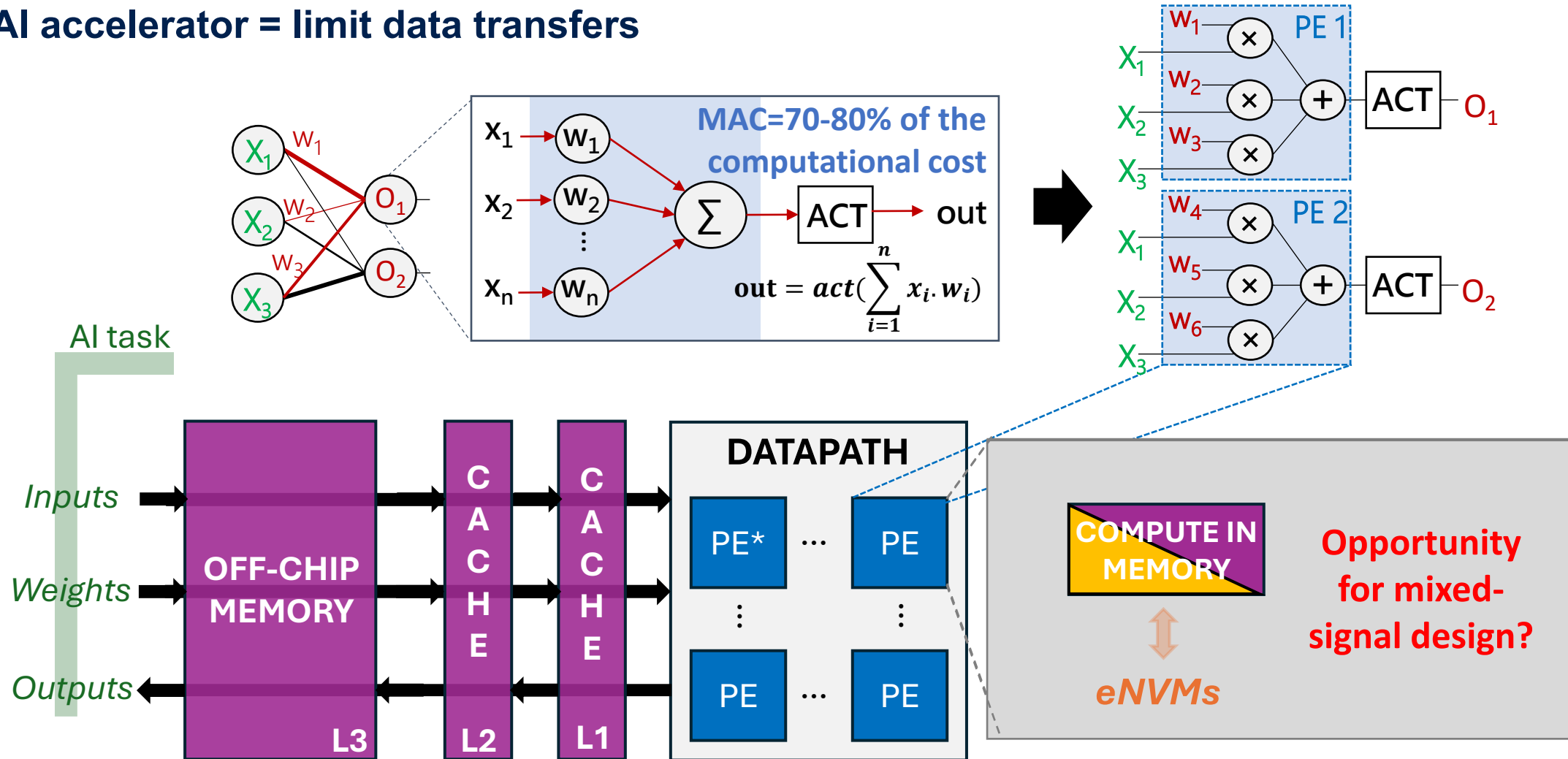


Outline

- AI accelerators: from digital processors to Compute-In-Memory (CIM):
 - Design overview (with a focus on **mixed-signal** topologies)
- Our work on reliable mixed-signal CIM systems:
 - How to evaluate the **accuracy** of mixed-signal CIM?
 - **Self-calibration** for noise and temperature compensation
 - **Did we do a good design?**
- Conclusions and perspectives

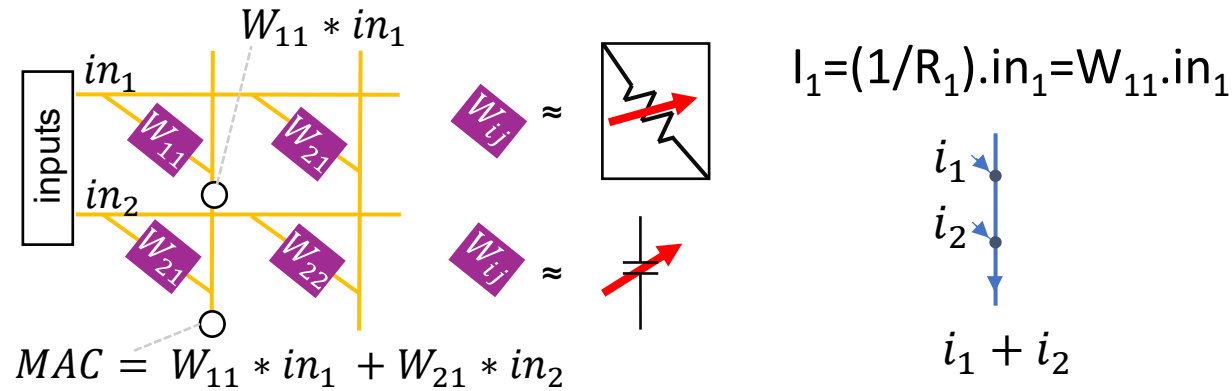
A typical digital AI accelerator

- AI accelerator = limit data transfers

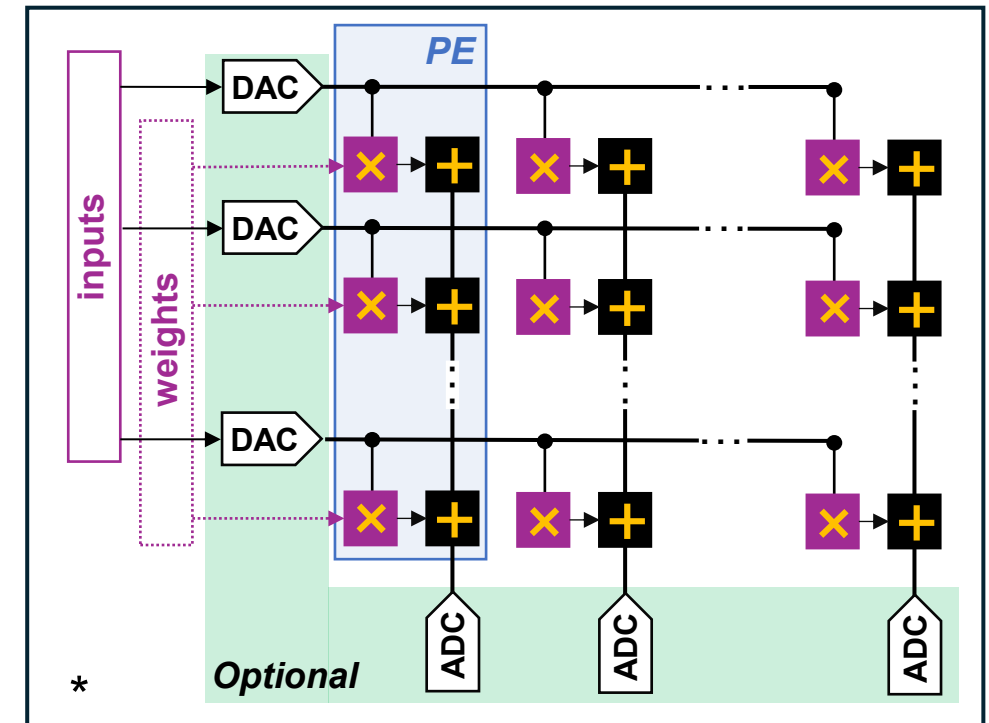
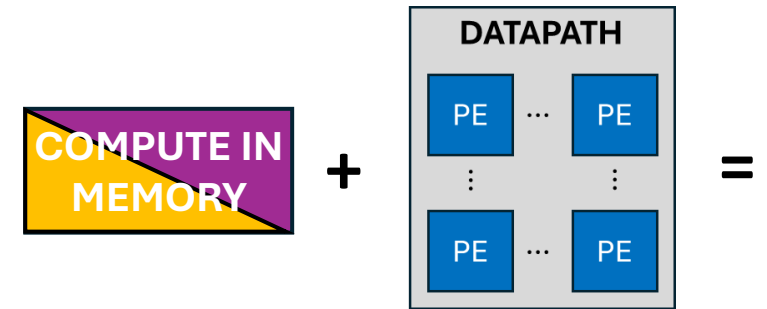


Analog compute in memory arrays

- Based on basic **voltage** and **current** laws



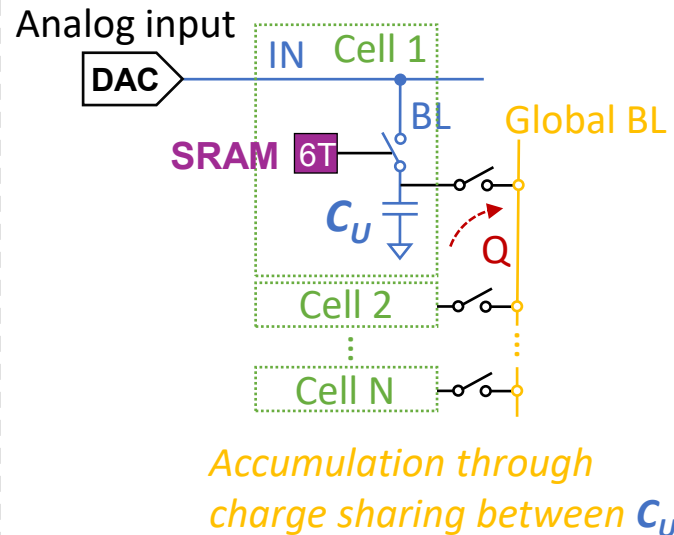
- How to measure the **performance** (op=MAC)?
 - How fast you go (ops/s) ↗ **array size, clock**
 - How efficient you are (ops/s/W) ↘ **cell power**
 - How much area it takes (ops/s/mm²) ↘ **cell size**



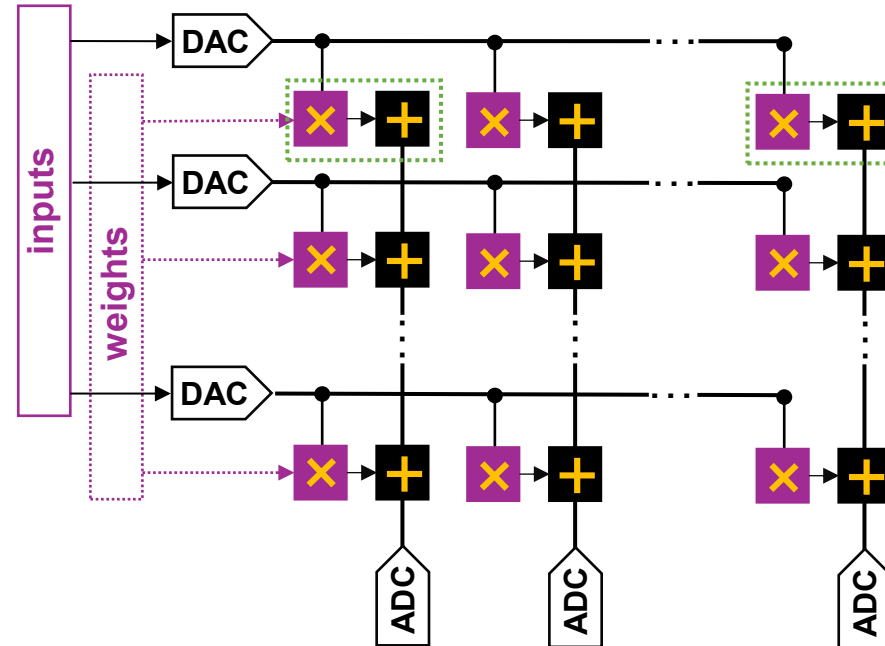
Different types of mixed-signal CIM

CMOS-based (capacitance or resistance)

(Charge-based example [1])

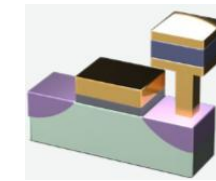


[1] N. Verma et al., "Compute-In-Memory: advances and prospects," SSC mag, 2019.



eNVM – based (emerging non-volatile memories)

(Example using ferroelectric eNVMs [2])

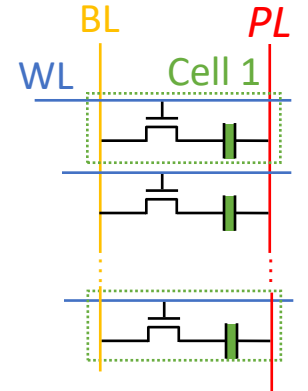


1T-1C

FeRAM (feCAP)

- Two polarization states, storing "1" or "0", programmed through **PL line**

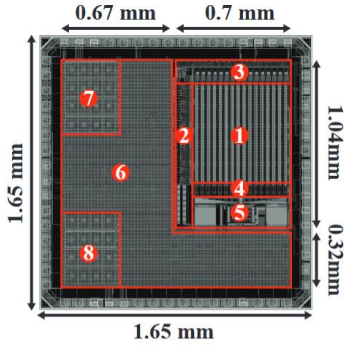
- Reading the charge value on **BL** (destructive)



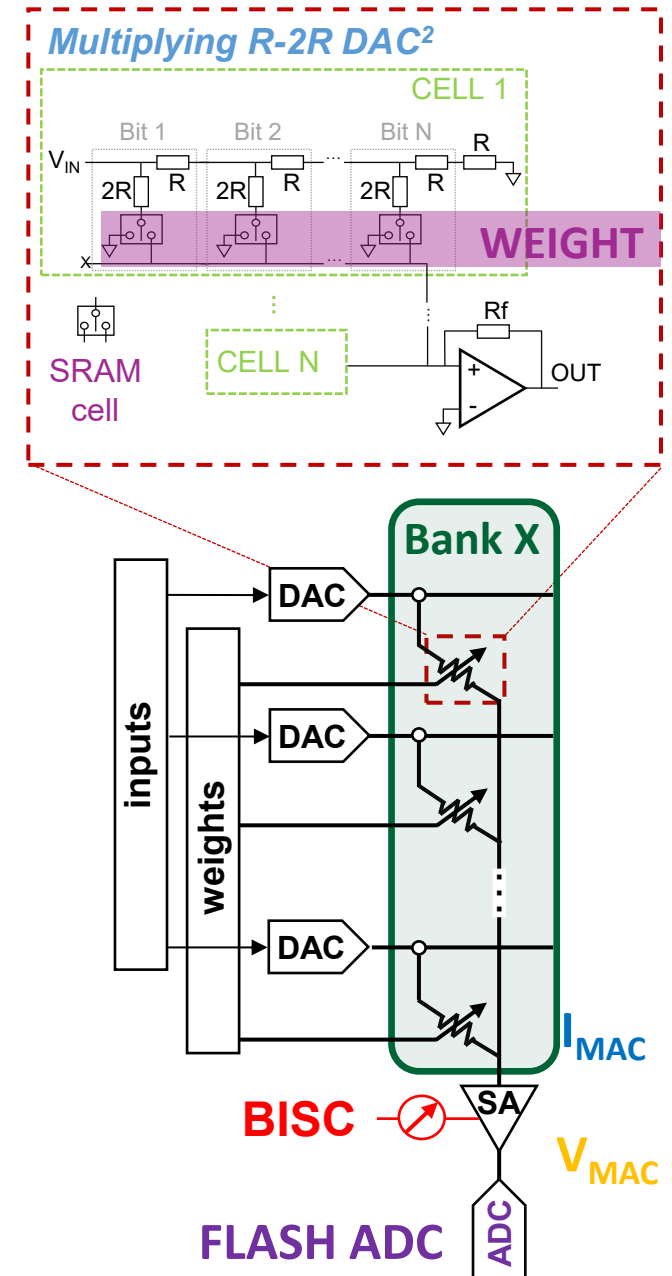
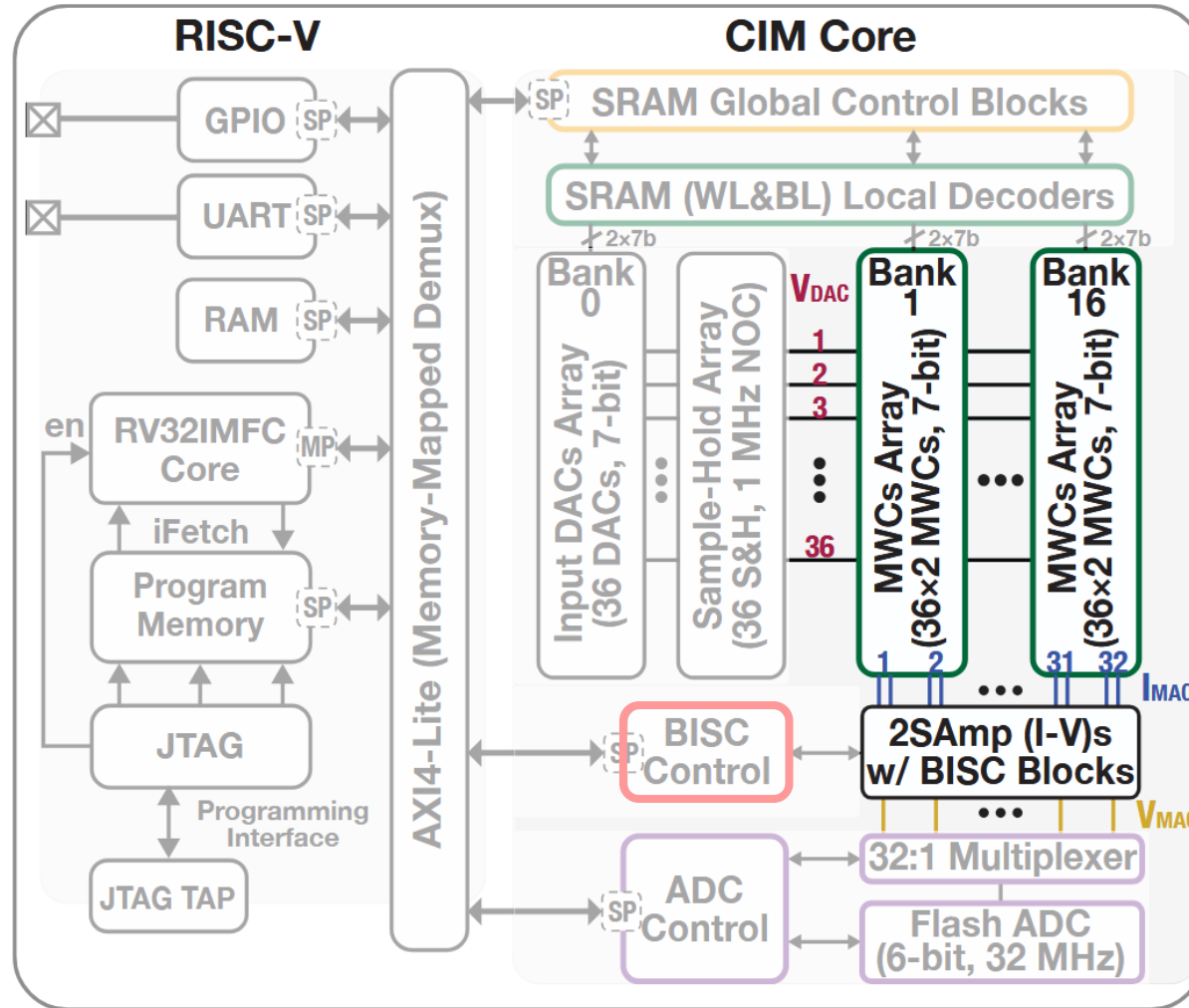
[2] J. Duan et al., "A full spectrum of 3D ferroelectric memory architectures shaped by polarization sensing," preprint, 2025.

- **Ok, but what about computational accuracy ?**

Case study: A-core CIM chip



- GF22nm
- 36x32 CIM block
- 6-bit accuracy
- RISC-V control
- Built-in self-calibration



Measure the accuracy your ANA-CIM core

- We can define the **compute SNR (SNR_T)**
- How to optimize the **compute SNR**?
 - Better ADC SNR? Increase resolution
 - “Best” design: analog-limited[1] :

👍 Rule #1: $SNR_{ADC} = SNR_A + 9dB$

- What is a “practical” value for **SNR_A** ?
 - The compute SNR depends on each DNN layer

$$10dB \leq SNR_T \leq 40 dB$$

- Rule of thumb: we try to **limit the accuracy degradation compared to software at 5%**

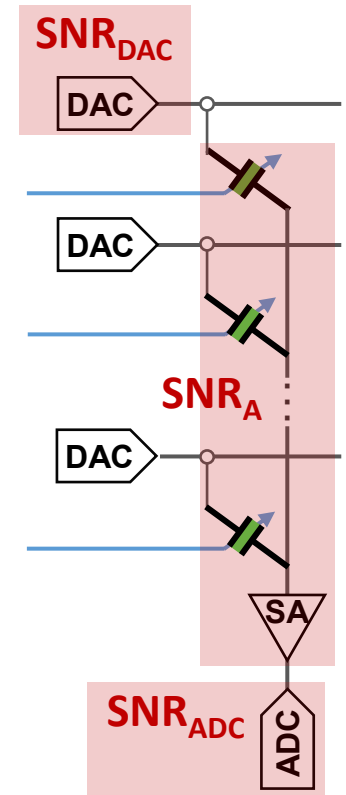
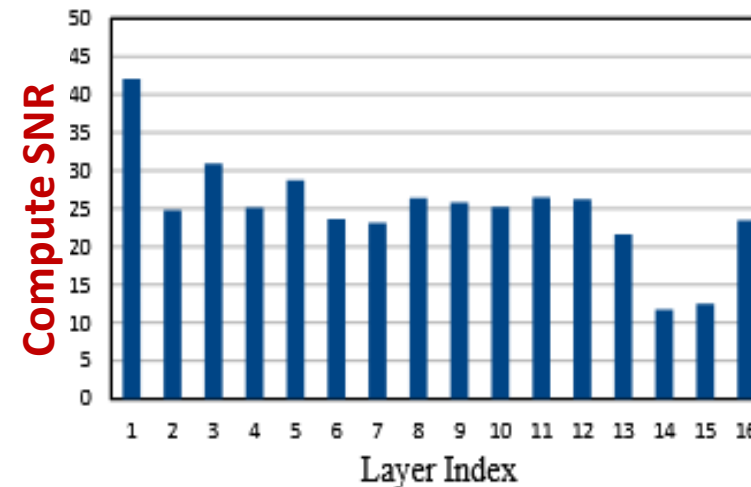
👍 Rule #2: fix $SNR_T \approx SNR_A \approx 20dB$

➔ $SNR_{ADC} \approx 30 dB \Rightarrow ENOB = 4.6 bits$

$$SNR_T = \left[\frac{1}{SNR_A} + \frac{1}{SNR_{ADC}} \right]^{-1}$$

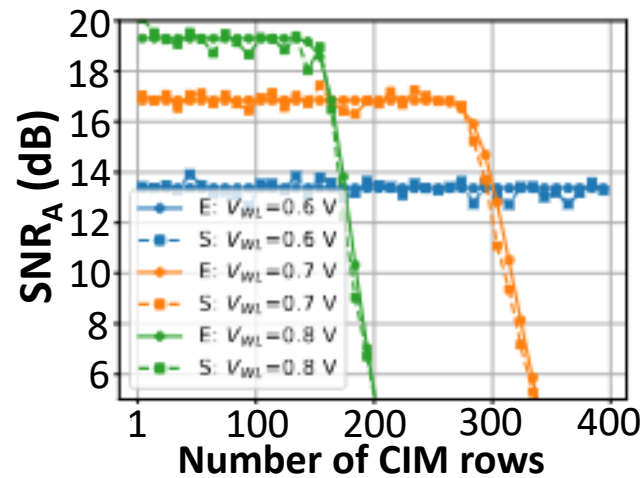
$$SNR_{ADC} \gg SNR_A$$

Example with VGG 16 [1]

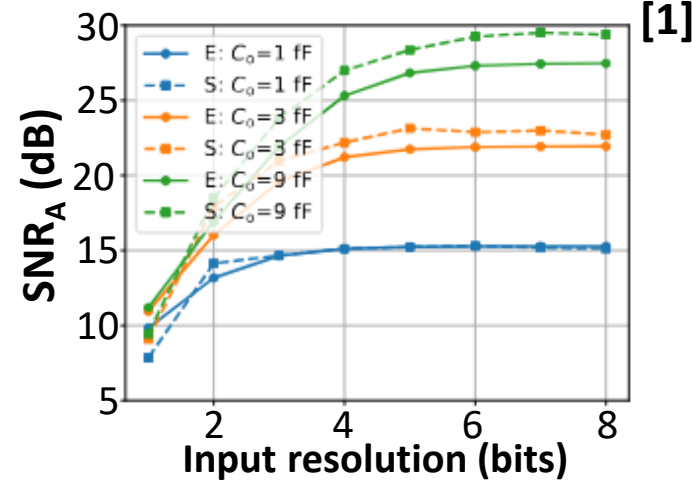


Mixed-signal CIM: a need for calibration

CMOS CIM

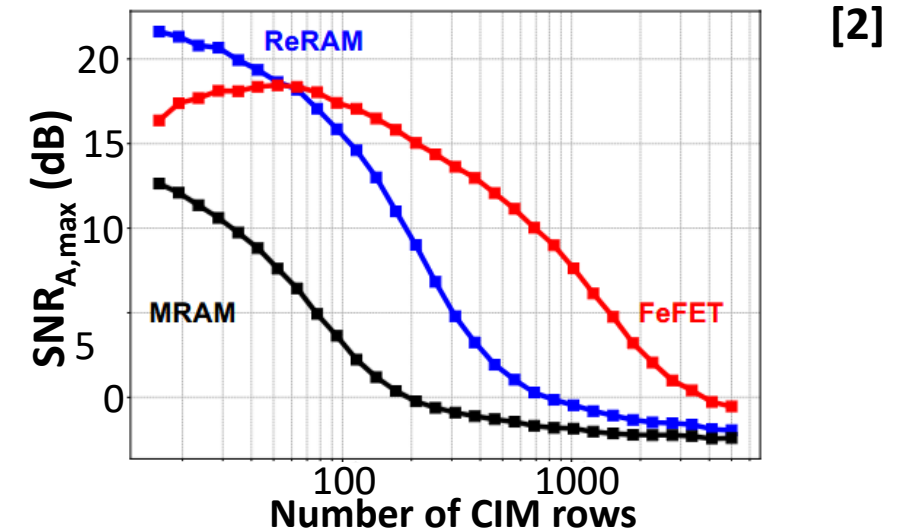


Limited by architecture & noise in charge-sharing or current accumulation



Mitigation with typical design trade offs (increase cap for better SNR)

eNVM CIM



Limited by process variations, mismatches, and thermal noise

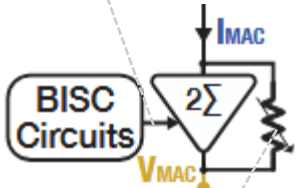


It is difficult to attain more than 20dB of SNR without calibration

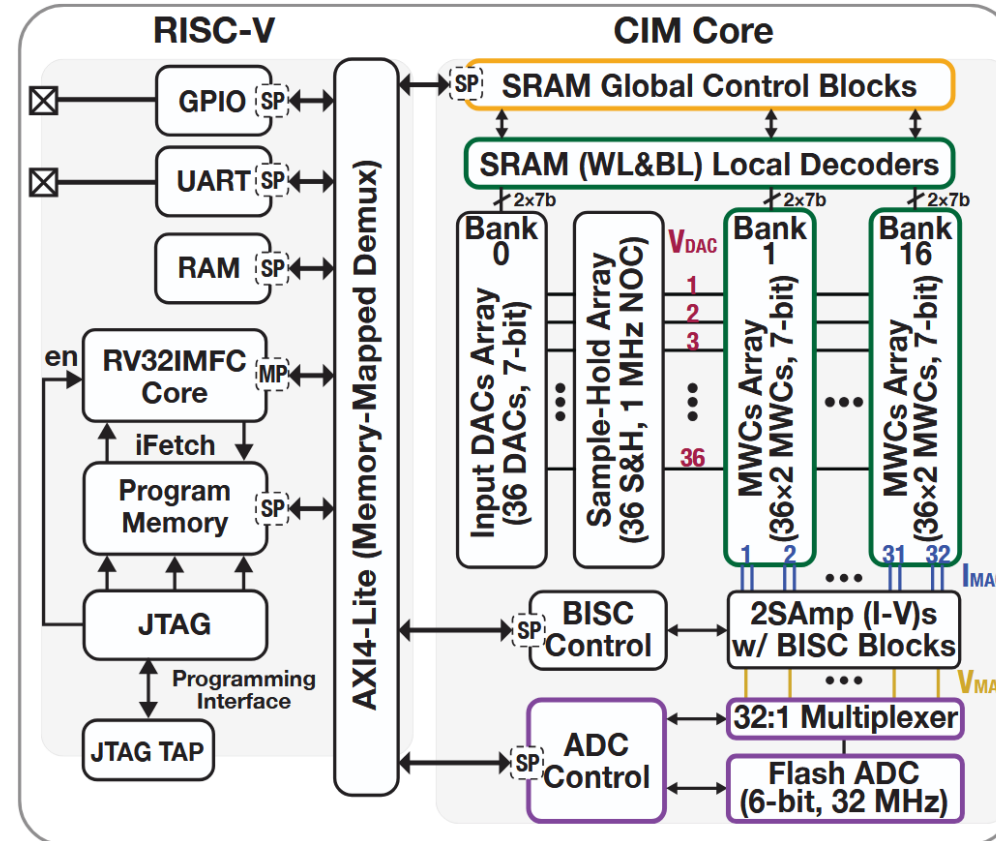
Built-in Self Calibration: principle

Offline (off-chip)

Characterize the link between gain and offset errors with the calibration voltage of the amplifier

$$V'_{CAL} = V_{CAL} - \frac{\hat{\epsilon}_{tot} - \beta_D}{\alpha_D C_{ADC}}$$


$$R'_{SA} = \frac{\alpha_D R_{SA}}{\hat{g}_{tot}}$$

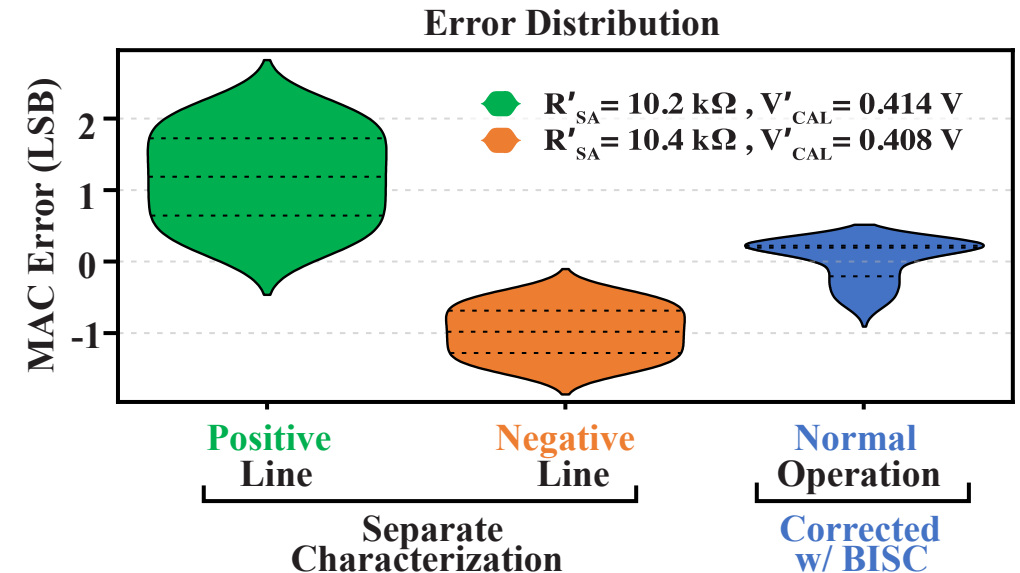
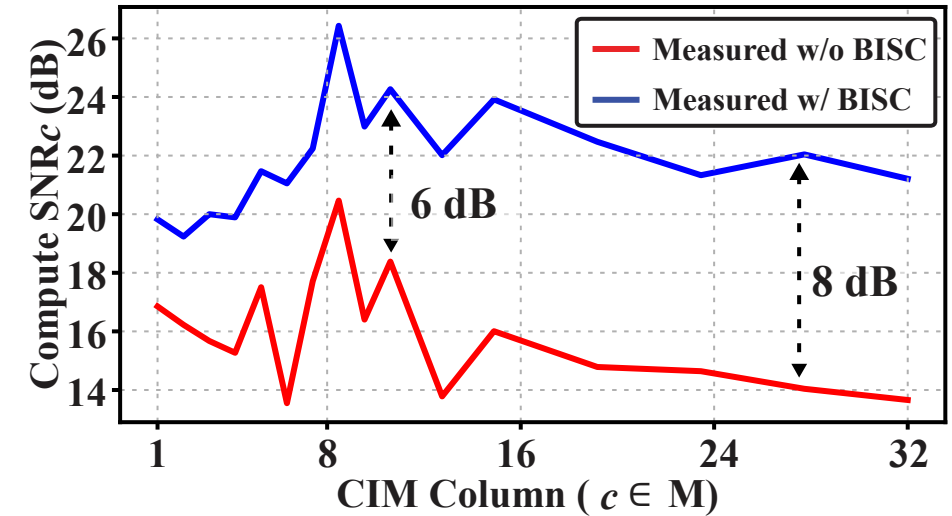


Online (on-chip)

- 1 Generate test vectors (a set of known MAC operations) with the RISC-V processor
- 2 Calculate the error on the whole chain and estimate the compute SNR (SNR_T)
- 3 Apply correction factors to optimize SNR_T

SNR calibration

- Before calibration
 - Low compute SNR (14-20dB)
 - Large error (+2 LSB...)
- After calibration
 - Reduced computation error
 - The compute SNR is between **19-26dB**
 - The error is contained inside **± 1 LSB** after ADC quantization

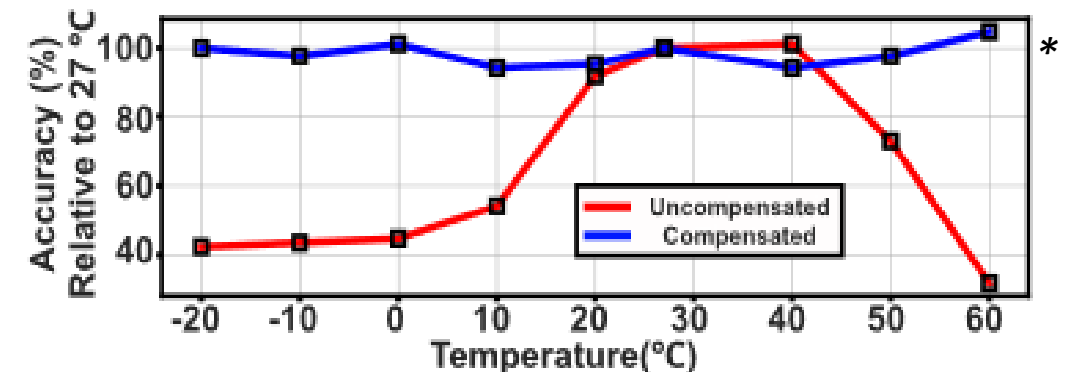
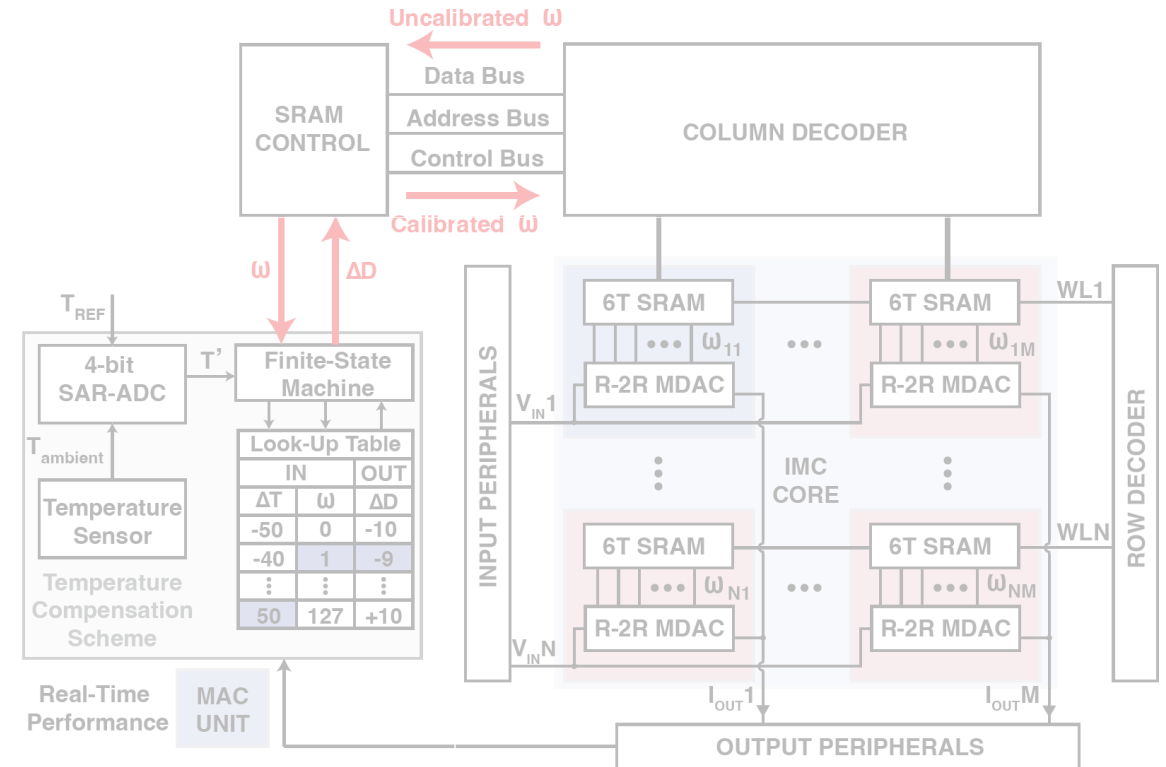


Temperature compensation

- Temperature **greatly** impacts the accuracy of mixed-signal CIM cores
 - Error build up as each component has a slightly different Temp. coeff.

$$R(T) = R_0 [1 + \alpha(T - T_R)]$$

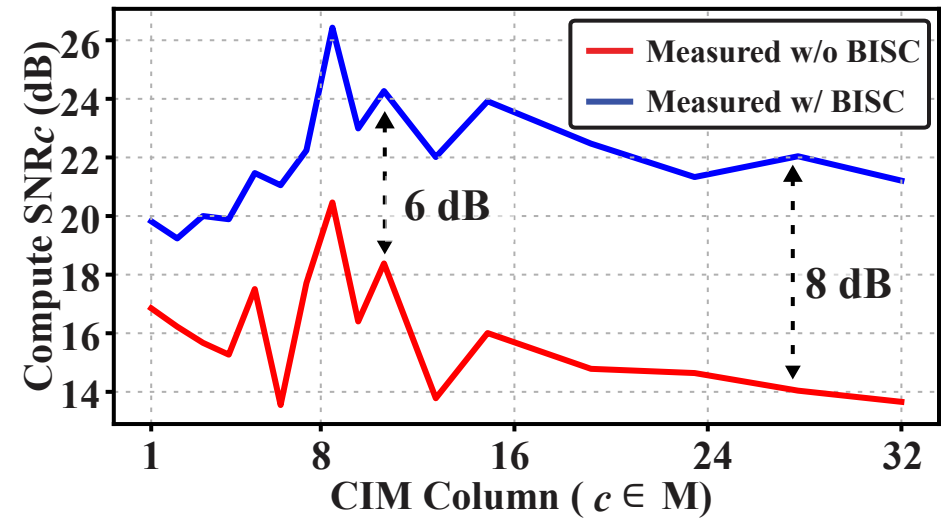
- Our strategy: rewrite the stored weights to compensate for these variations
 - On-chip temp. sensor + LUT + mem write
 - Very effective (almost no accuracy loss)
 - Can be costly if frequent rewrite (but temperature variations are slow)



* Measured for MNIST task

Did we do a good design?

- This depends how we look at it:
 - “Required accuracy”: **yes**, we have a compute SNR of 20dB+ for most columns
 - System-wise?
 - $SNR_A = 34$ dB (5.4 ENOB) **$SNR_T = 26,7$ dB**
 - $SNR_{ADC} = 31$ dB (4.9 ENOB) **Syst. ENOB: 4.1**



👍 Rule #1: $SNR_{ADC} = SNR_A + 9dB$

👍 Rule #2: fix $SNR_A \approx 20dB$

- **Lessons learned**

- To target the “required” 20 dB of SNR, 4-bit weights and activations seem sufficient
 - **Yet, 5% accuracy loss is a lot compared to digital implementations**
- Take care of your ADC design!
 - Limiting factor in our case (no good pre-amplifier in the flash ADC)
- We have uncalibrated variations left
 - Mismatch? Interferences between columns?

Conclusions and perspectives

- Test and reliability of mixed-signal CIM is crucial to ensure the required computation accuracy
 - There are **large differences** between the *required DNN accuracy* and the *CIM system's accuracy*
 - The situation might get worse with **emerging technologies**

Parameter	Software baseline	"Required" DNN accuracy	Optimal design (6b target)	Current design (no BISC)	Current design (with BISC)
SNR_A (dB)	'40'	20	38	14 - 20	20-26
System ENOB (bits)	'6.3'	3	6	2.3 - 3	3.3 - 4

- Calibration methodologies are required
 - Compensate for noise, mismatches, temperature, process...
 - **Design guidelines** and **existing automated strategies** are there to build your system

Thank you for your attention!

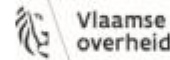
martin.andraud@uclouvain.be



Co-funded by
the European Union



LAND KÄRNTEN



BUSINESS
FINLAND

